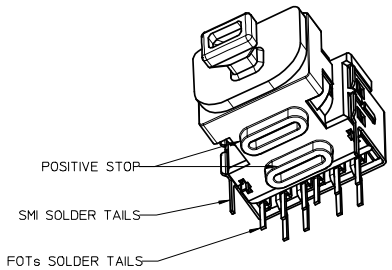
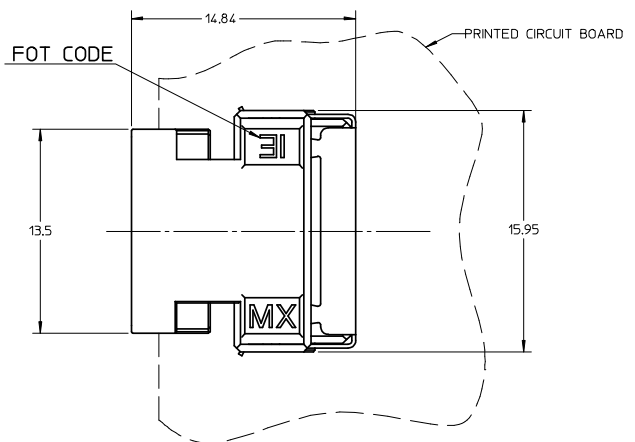
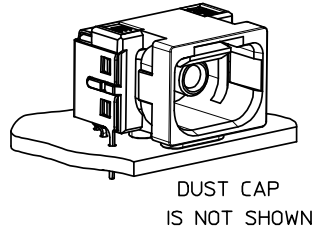


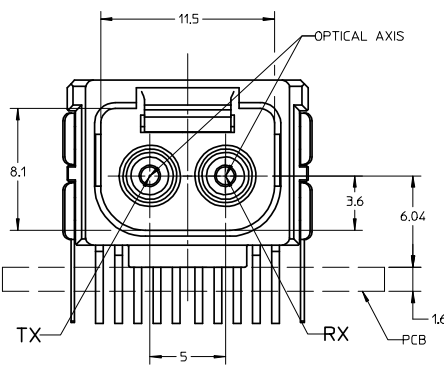
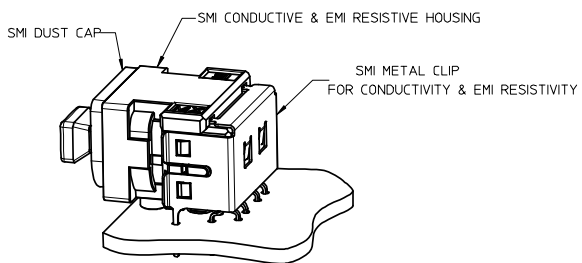
SMI/SMT TRANSCEIVER ASSEMBLY P/N	FOT's TYPE	FOT CODE
1061082100	IEEE-1394/ DIGITAL FDL300K	IE
1061083100	10/100 ETHERNET EDL300K	EL
1061084100	INDUSTRIAL DATA LINK IDL300K	ID



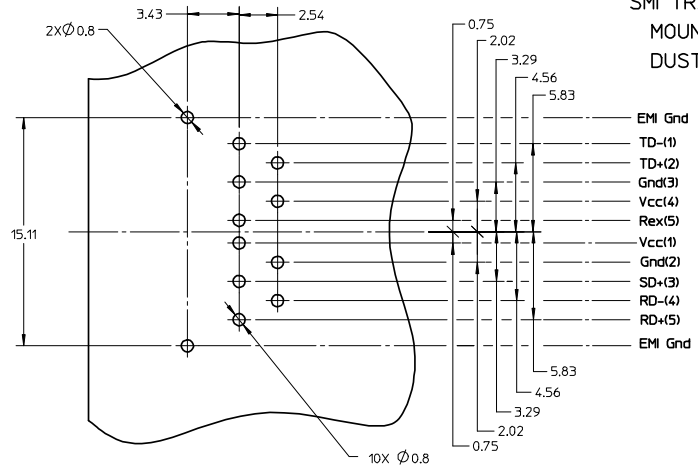
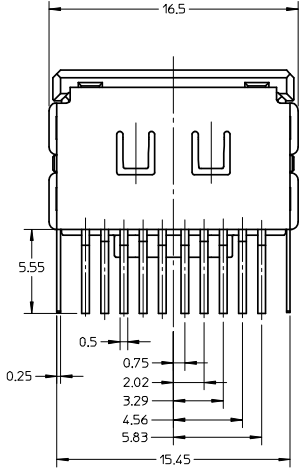
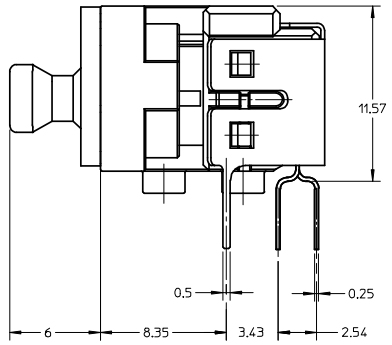
ISOMETRIC VIEWS
SCALE 2.5:1



DUST CAP NOT SHOWN



SMI TRANSCEIVER ASSEMBLY
MOUNTED ON THE PCB
DUST CAP NOT SHOWN



RECOMMENDED PCB LAYOUT
DIMENSIONS TOLERANCE: ±0.1mm

NOTES:

- ALL DIMENSIONS ARE FOR REFERENCE ONLY EXCEPT FOR RECOMMENDED PCB LAYOUT.
- ATTACHMENT OF THIS COMPONENT TO THE PCB VIA HOT BAR/LASER OR IR SOLDERING. RE-FLOW OVEN SOLDERING IS NOT APPROVED AT THIS TIME.

ENTER DESCRIPTION EC NO: MF2008-0555 DRWNS:SMIGO 2008/06/11 CHKD: 2008/06/11 APPR:SMIGO 2008/06/26	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		mm	INCH	DRAWN BY BG	DATE 09/12/06	TITLE SMI TRANSCEIVER ASSEMBLY THROUGH- HOLE SOLDERING			
4 PLACES ±	---	±	---	CHECKED BY SE	DATE 9/15/06				
3 PLACES ±	---	±	---	APPROVED BY DATE	DATE	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-106108-X100	SHEET NO. 1 OF 1
2 PLACES ±	---	±	---	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
1 PLACE ±	---	±	---						
REVISIONS		ANGULAR ±1/2°		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					